

# **Device Modeling Report**

COMPONENTS:MAGNETIC CORE  
PART NUMBER:HS72  
MANUFACTURER:TDK



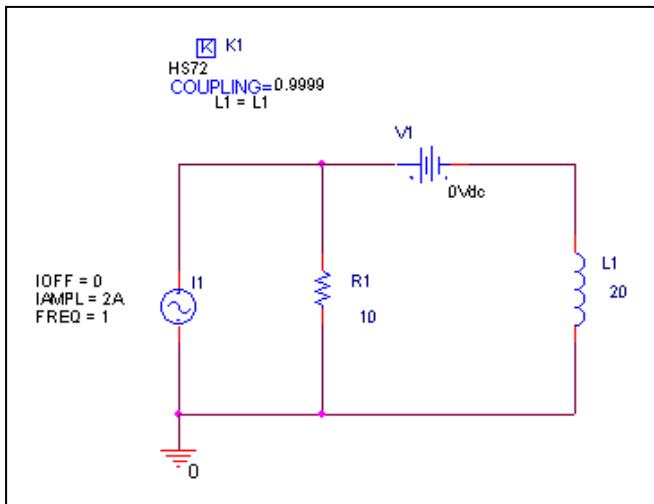
**Bee Technologies Inc.**

## MAGNETIC CORE

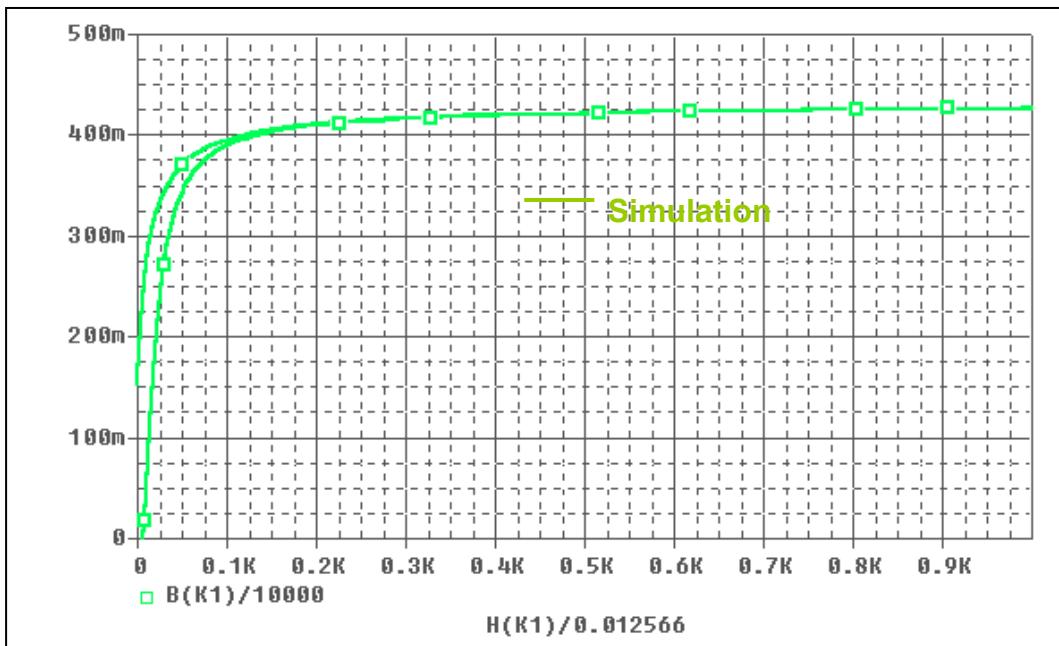
Pspice model parameter	Model description
A	thermal energy parameter
K	domain anisotropy parameter
C	domain flexing parameter
MS	magnetization saturation

# Hysteresis Curve Characteristics

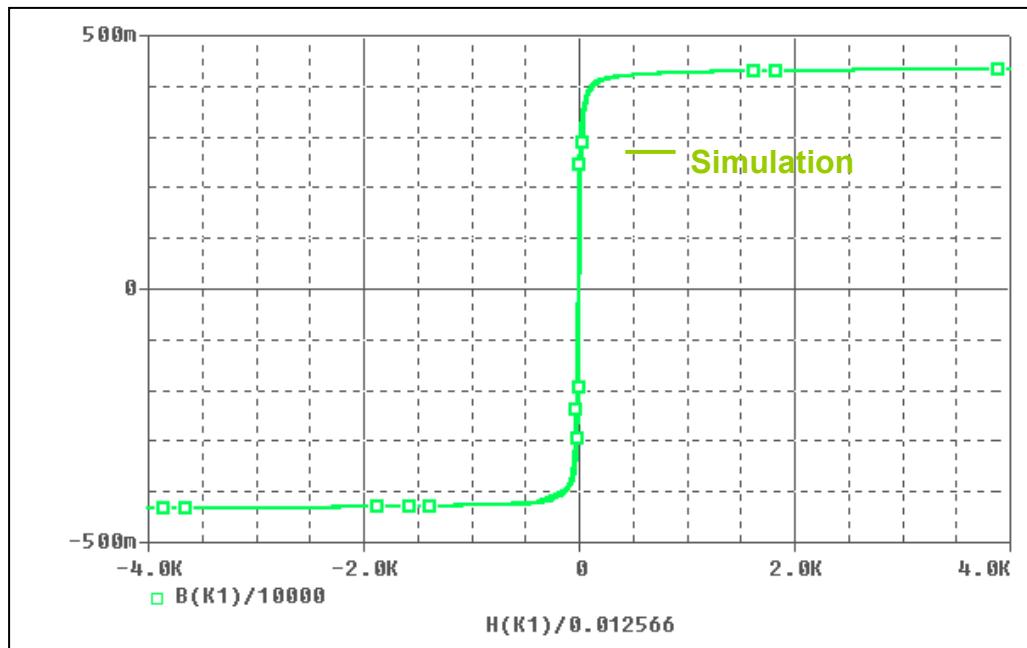
## Evaluation Circuit



## Simulation result



**Simulation result**



**Comparison Table**

H(A/m)	B(mT) Measurement	B(mT) Simulation	%Error
50	360	370.567	2.935
100	400	394.686	1.329
200	412	411.067	0.226
300	417	416.654	0.083
400	420	419.728	0.065
500	422	422.73	0.173
600	425	423.875	0.265
700	427	425.02	0.464
800	428	425.888	0.493
900	430	426.534	0.806
1000	430	427.158	0.661